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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	50MHz
Connectivity	I ² C, SMBus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	20
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 12x10/12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-VFQFN Exposed Pad
Supplier Device Package	24-QFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm8bb31f64g-a-qfn24

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3.2 Power

All internal circuitry draws power from the VDD supply pin. External I/O pins are powered from the VIO supply voltage (or VDD on devices without a separate VIO connection), while most of the internal circuitry is supplied by an on-chip LDO regulator. Control over the device power can be achieved by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and placed in low power mode. Digital peripherals, such as timers and serial buses, have their clocks gated off and draw little power when they are not in use.

Table 3.1. Power Modes

Power Mode	Details	Mode Entry	Wake-Up Sources
Normal	Core and all peripherals clocked and fully operational		
ldle	 Core halted All peripherals clocked and fully operational Code resumes execution on wake event 	Set IDLE bit in PCON0	Any interrupt
Suspend	 Core and peripheral clocks halted HFOSC0 and HFOSC1 oscillators stopped Regulator in normal bias mode for fast wake Timer 3 and 4 may clock from LFOSC0 Code resumes execution on wake event 	1. Switch SYSCLK to HFOSC0 2. Set SUSPEND bit in PCON1	 Timer 4 Event SPI0 Activity I2C0 Slave Activity Port Match Event Comparator 0 Rising Edge CLUn Interrupt-Enabled Event
Stop	 All internal power nets shut down Pins retain state Exit on any reset source	1. Clear STOPCF bit in REG0CN 2. Set STOP bit in PCON0	Any reset source
Snooze	 Core and peripheral clocks halted HFOSC0 and HFOSC1 oscillators stopped Regulator in low bias current mode for energy savings Timer 3 and 4 may clock from LFOSC0 Code resumes execution on wake event 	1. Switch SYSCLK to HFOSC0 2. Set SNOOZE bit in PCON1	 Timer 4 Event SPI0 Activity I2C0 Slave Activity Port Match Event Comparator 0 Rising Edge CLUn Interrupt-Enabled Event
Shutdown	 All internal power nets shut down Pins retain state Exit on pin or power-on reset	1. Set STOPCF bit in REG0CN 2. Set STOP bit in PCON0	RSTb pin reset Power-on reset

3.3 I/O

Digital and analog resources are externally available on the device's multi-purpose I/O pins. Port pins P0.0-P2.3 can be defined as general-purpose I/O (GPIO), assigned to one of the internal digital resources through the crossbar or dedicated channels, or assigned to an analog function. Port pins P2.4 to P3.7 can be used as GPIO. Additionally, the C2 Interface Data signal (C2D) is shared with P3.0 or P3.7, depending on the package option.

The port control block offers the following features:

- Up to 29 multi-functions I/O pins, supporting digital and analog functions.
- · Flexible priority crossbar decoder for digital peripheral assignment.
- · Two drive strength settings for each port.
- State retention feature allows pins to retain configuration through most reset sources.
- Two direct-pin interrupt sources with dedicated interrupt vectors (INT0 and INT1).
- · Up to 24 direct-pin interrupt sources with shared interrupt vector (Port Match).

I2C Slave (I2CSLAVE0)

The I2C Slave interface is a 2-wire, bidirectional serial bus that is compatible with the I2C Bus Specification 3.0. It is capable of transferring in high-speed mode (HS-mode) at speeds of up to 3.4 Mbps. Firmware can write to the I2C interface, and the I2C interface can autonomously control the serial transfer of data. The interface also supports clock stretching for cases where the core may be temporarily prohibited from transmitting a byte or processing a received byte during an I2C transaction. This module operates only as an I2C slave device.

The I2C module includes the following features:

- Standard (up to 100 kbps), Fast (400 kbps), Fast Plus (1 Mbps), and High-speed (3.4 Mbps) transfer speeds
- · Support for slave mode only
- · Clock low extending (clock stretching) to interface with faster masters
- · Hardware support for 7-bit slave address recognition
- Hardware support for multiple slave addresses with the option to save the matching address in the receive FIFO

16-bit CRC (CRC0)

The cyclic redundancy check (CRC) module performs a CRC using a 16-bit polynomial. CRC0 accepts a stream of 8-bit data and posts the 16-bit result to an internal register. In addition to using the CRC block for data manipulation, hardware can automatically CRC the flash contents of the device.

The CRC module is designed to provide hardware calculations for flash memory verification and communications protocols. The CRC module supports the standard CCITT-16 16-bit polynomial (0x1021), and includes the following features:

- · Support for CCITT-16 polynomial
- · Byte-level bit reversal
- · Automatic CRC of flash contents on one or more 256-byte blocks
- · Initial seed selection of 0x0000 or 0xFFFF

Configurable Logic Units (CLU0, CLU1, CLU2, and CLU3)

The Configurable Logic block consists of multiple Configurable Logic Units (CLUs). CLUs are flexible logic functions which may be used for a variety of digital functions, such as replacing system glue logic, aiding in the generation of special waveforms, or synchronizing system event triggers.

- Four configurable logic units (CLUs), with direct-pin and internal logic connections
- Each unit supports 256 different combinatorial logic functions (AND, OR, XOR, muxing, etc.) and includes a clocked flip-flop for synchronous operations
- · Units may be operated synchronously or asynchronously
- · May be cascaded together to perform more complicated logic functions
- Can operate in conjunction with serial peripherals such as UART and SPI or timing peripherals such as timers and PCA channels
- · Can be used to synchronize and trigger multiple on-chip resources (ADC, DAC, Timers, etc.)
- Asynchronous output may be used to wake from low-power states

3.7 Analog

12/10-Bit Analog-to-Digital Converter (ADC0)

The ADC is a successive-approximation-register (SAR) ADC with 12- and 10-bit modes, integrated track-and hold and a programmable window detector. The ADC is fully configurable under software control via several registers. The ADC may be configured to measure different signals using the analog multiplexer. The voltage reference for the ADC is selectable between internal and external reference sources.

- · Up to 20 external inputs
- Single-ended 12-bit and 10-bit modes
- Supports an output update rate of up to 400 ksps in 12-bit mode
- Channel sequencer logic with direct-to-XDATA output transfers
- · Operation in a low power mode at lower conversion speeds
- Asynchronous hardware conversion trigger, selectable between software, external I/O and internal timer and configurable logic sources
- · Output data window comparator allows automatic range checking
- · Support for output data accumulation
- Conversion complete and window compare interrupts supported
- Flexible output data formatting
- Includes a fully-internal fast-settling 1.65 V reference and an on-chip precision 2.4 / 1.2 V reference, with support for using the supply as the reference, an external reference and signal ground
- · Integrated temperature sensor

12-Bit Digital-to-Analog Converters (DAC0, DAC1, DAC2, DAC3)

The DAC modules are 12-bit Digital-to-Analog Converters with the capability to synchronize multiple outputs together. The DACs are fully configurable under software control. The voltage reference for the DACs is selectable between internal and external reference sources.

- · Voltage output with 12-bit performance
- Supports an update rate of 200 ksps
- · Hardware conversion trigger, selectable between software, external I/O and internal timer and configurable logic sources
- · Outputs may be configured to persist through reset and maintain output state to avoid system disruption
- · Multiple DAC outputs can be synchronized together
- DAC pairs (DAC0 and 1 or DAC2 and 3) support complementary output waveform generation
- Outputs may be switched between two levels according to state of configurable logic / PWM input trigger
- · Flexible input data formatting
- Supports references from internal supply, on-chip precision reference, or external VREF pin

4.1.2 Power Consumption

Table 4.2. Power Consumption

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Digital Core Supply Current			<u> </u>			
Normal Mode-Full speed with code	I _{DD}	F _{SYSCLK} = 49 MHz ²	_	TBD	TBD	mA
executing from flash		F _{SYSCLK} = 24.5 MHz ²	_	4.5	TBD	mA
		F _{SYSCLK} = 1.53 MHz ²	_	615	TBD	μA
		F _{SYSCLK} = 80 kHz ³	_	155	TBD	μA
dle Mode-Core halted with periph-	I _{DD}	F _{SYSCLK} = 49 MHz ²	_	TBD	TBD	mA
erals running		F _{SYSCLK} = 24.5 MHz ²	_	2.8	TBD	mA
		F _{SYSCLK} = 1.53 MHz ²	_	455	TBD	μA
		F _{SYSCLK} = 80 kHz ³	_	145	TBD	μA
Suspend Mode-Core halted and	I _{DD}	LFO Running	_	125	TBD	μA
nigh frequency clocks stopped, Supply monitor off.		LFO Stopped	_	120	TBD	μA
Snooze Mode-Core halted and	I _{DD}	LFO Running	_	26	TBD	μA
nigh frequency clocks stopped. Regulator in low-power state, Sup- oly monitor off.		LFO Stopped	_	21	TBD	μA
Stop Mode—Core halted and all clocks stopped,Internal LDO On, Supply monitor off.	I _{DD}		_	120	TBD	μА
Shutdown Mode—Core halted and all clocks stopped,Internal LDO Dff, Supply monitor off.	I _{DD}		_	0.2	_	μА
Analog Peripheral Supply Currents						
High-Frequency Oscillator 0	I _{HFOSC0}	Operating at 24.5 MHz, T _A = 25 °C	_	55	_	μА
High-Frequency Oscillator 1	I _{HFOSC1}	Operating at 49 MHz,	_	TBD	_	μA
		T _A = 25 °C				
ow-Frequency Oscillator	I _{LFOSC}	Operating at 80 kHz,	_	5	_	μA
		T _A = 25 °C				
ADC0 ⁴	I _{ADC}	TBD	_	TBD	TBD	μA
nternal ADC0 Reference ⁵	I _{VREFFS}	Normal Power Mode	_	680	TBD	μA
		Low Power Mode	_	160	TBD	μA
On-chip Precision Reference	I _{VREFP}		_	75	_	μA
Геmperature Sensor	I _{TSENSE}		_	75	120	μA
Digital-to-Analog Converters (DAC0, DAC1) ⁶	I _{DAC}		_	125	_	μA

4.1.10 Voltage Reference

Table 4.10. Voltage Reference

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Internal Fast Settling Reference						
Output Voltage	V _{REFFS}	-S		1.65	1.68	V
(Full Temperature and Supply Range)						
Temperature Coefficient	TC _{REFFS}		_	50	_	ppm/°C
Turn-on Time	t _{REFFS}		_	_	1.5	μs
Power Supply Rejection	PSRR _{REF}		_	400	_	ppm/V
On-chip Precision Reference			I			
Valid Supply Range	V_{DD}	1.2 V Output	2.2	_	3.6	V
		2.4 V Output	2.7	_	3.6	V
Output Voltage	V _{REFP}	1.2 V Output, T = 25 °C	TBD	1.2	TBD	V
		2.4 V Output, T = 25 °C	TBD	2.4	TBD	V
Turn-on Time, settling to 0.5 LSB	t _{VREFP}	4.7 μF tantalum + 0.1 μF ceramic bypass on VREF pin	_	3	_	ms
		0.1 μF ceramic bypass on VREF pin	_	100	_	μs
Load Regulation	LR _{VREFP}	Load = 0 to 200 µA to GND	_	TBD	_	μV/μΑ
Load Capacitor	C _{VREFP}	Load = 0 to 200 µA to GND	0.1	_	_	μF
Short-circuit current	ISC _{VREFP}		_	_	8	mA
Power Supply Rejection	PSRR _{VRE}		_	TBD	_	ppm/V
External Reference		1	1	I	ı	
Input Current	I _{EXTREF}	ADC Sample Rate = 800 ksps; VREF = 3.0 V	_	5	_	μА

4.1.12 DACs

Table 4.12. DACs

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Resolution	N _{bits}			12		Bits
Throughput Rate	f _S		_	_	200	ksps
Integral Nonlinearity	INL		TBD	±0.5	TBD	LSB
Differential Nonlinearity	DNL		TBD	±5	TBD	LSB
Output Noise	VREF = 2.4 V f _S = 0.1 Hz to 300 kHz		_	110	_	μV _{RMS}
Slew Rate	SLEW		_	±1	_	V/µs
Output Settling Time to 1 LSB	tsettle	V _{OUT} change between 25% and 75% Full Scale	_	2.6	5	μs
Power-on Time	t _{PWR}		_	_	10	μs
Voltage Reference Range	V _{REF}		1.15	_	V_{DD}	V
Power Supply Rejection Ratio	PSRR	DC, V _{OUT} = 50% Full Scale	_	110	_	dB
		1 kHz, V _{OUT} = 50% Full Scale	_	60	_	dB
Total Harmonic Distortion	THD	V _{OUT} = 10 kHz sine wave, 10% to 90%	60	_	_	dB
Offset Error	E _{OFF}	VREF = 2.4 V	TBD	±0.5	TBD	LSB
Offset Temperature Coefficient	TC _{OFF}		_	TBD	_	ppm/°C
Full-Scale Error	E _{FS}	VREF = 2.4 V	TBD	±5	TBD	LSB
Full-Scale Error Tempco	TC _{FS}		_	TBD	_	ppm/°C
External Load Impedance	R _{LOAD}		2	_	_	kΩ
External Load Capacitance	C _{LOAD}		TBD	_	100	pF
Load Regulation		V _{OUT} = 50% Full Scale	_	100	TBD	μV/mA

5.2 Debug

The diagram below shows a typical connection diagram for the debug connections pins. The pin sharing resistors are only required if the functionality on the C2D (a GPIO pin) and the C2CK (RSTb) is routed to external circuitry. For example, if the RSTb pin is connected to an external switch with debouncing filter or if the GPIO sharing with the C2D pin is connected to an external circuit, the pin sharing resistors and connections to the debug adapter must be placed on the hardware. Otherwise, these components and connections can be omitted.

For more information on debug connections, see the example schematics and information available in AN127: "Pin Sharing Techniques for the C2 Interface." Application notes can be found on the Silicon Labs website (http://www.silabs.com/8bit-appnotes) or in Simplicity Studio.

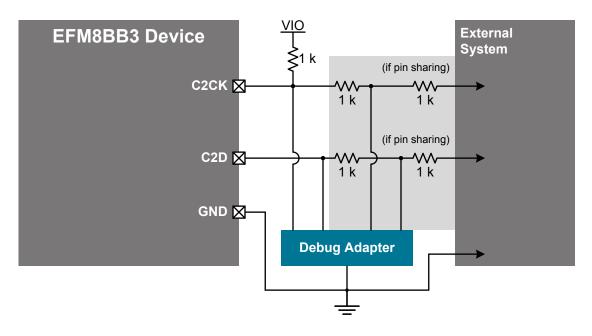


Figure 5.2. Debug Connection Diagram

5.3 Other Connections

Other components or connections may be required to meet the system-level requirements. Application Note AN203: "8-bit MCU Printed Circuit Board Design Notes" contains detailed information on these connections. Application Notes can be accessed on the Silicon Labs website (www.silabs.com/8bit-appnotes).

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
22	P1.3	Multifunction I/O	Yes	P1MAT.3	ADC0.9
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	
23	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	CMP0P.8
				CLU1A.11	CMP0N.8
				CLU2B.10	
				CLU3A.12	
				CLU3B.13	
24	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	CMP0P.7
				CLU1B.10	CMP0N.7
				CLU2A.11	
				CLU3B.12	
25	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU10UT	CMP0P.6
				CLU0A.12	CMP0N.6
				CLU1A.10	CMP1P.1
				CLU2A.10	CMP1N.1
26	P0.7	Multifunction I/O	Yes	P0MAT.7	ADC0.5
				INT0.7	CMP0P.5
				INT1.7	CMP0N.5
				CLU0B.11	CMP1P.0
				CLU1B.9	CMP1N.0
				CLU3A.11	
27	P0.6	Multifunction I/O	Yes	P0MAT.6	ADC0.4
				CNVSTR	CMP0P.4
				INT0.6	CMP0N.4
				INT1.6	
				CLU0A.11	
				CLU1B.8	
				CLU3A.10	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
28	P0.5	Multifunction I/O	Yes	P0MAT.5	ADC0.3
				INT0.5	CMP0P.3
				INT1.5	CMP0N.3
				UART0_RX	
				CLU0B.10	
				CLU1A.9	
29	P0.4	Multifunction I/O	Yes	P0MAT.4	ADC0.2
				INT0.4	CMP0P.2
				INT1.4	CMP0N.2
				UART0_TX	
				CLU0A.10	
				CLU1A.8	
30	P0.3	Multifunction I/O	Yes	P0MAT.3	XTAL2
				EXTCLK	
				INT0.3	
				INT1.3	
				CLU0B.9	
				CLU2B.10	
				CLU3A.9	
31	P0.2	Multifunction I/O	Yes	P0MAT.2	XTAL1
				INT0.2	ADC0.1
				INT1.2	CMP0P.1
				CLU0OUT	CMP0N.1
				CLU0A.9	
				CLU2B.8	
				CLU3A.8	
32	P0.1	Multifunction I/O	Yes	P0MAT.1	ADC0.0
				INT0.1	CMP0P.0
				INT1.1	CMP0N.0
				CLU0B.8	AGND
				CLU2A.9	
				CLU3B.9	
Center	GND	Ground			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
6	P3.7 /	Multifunction I/O /			
	C2D	C2 Debug Data			
7	P3.3	Multifunction I/O			DAC3
8	P3.2	Multifunction I/O			DAC2
9	P3.1	Multifunction I/O			DAC1
10	P3.0	Multifunction I/O			DAC0
11	P2.6	Multifunction I/O			ADC0.19
					CMP1P.8
					CMP1N.8
12	P2.5	Multifunction I/O		CLU3OUT	ADC0.18
					CMP1P.7
					CMP1N.7
13	P2.4	Multifunction I/O			ADC0.17
					CMP1P.6
					CMP1N.6
14	P2.3	Multifunction I/O	Yes	P2MAT.3	ADC0.16
				CLU1B.15	CMP1P.5
				CLU2B.15	CMP1N.5
				CLU3A.15	
15	P2.2	Multifunction I/O	Yes	P2MAT.2	ADC0.15
				CLU2OUT	CMP1P.4
				CLU1A.15	CMP1N.4
				CLU2B.14	
				CLU3A.14	
16	P2.1	Multifunction I/O	Yes	P2MAT.1	ADC0.14
				I2C0_SCL	CMP1P.3
				CLU1B.14	CMP1N.3
				CLU2A.15	
				CLU3B.15	
17	P2.0	Multifunction I/O	Yes	P2MAT.0	CMP1P.2
				I2C0_SDA	CMP1N.2
				CLU1A.14	
				CLU2A.14	
				CLU3B.14	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
18	P1.7	Multifunction I/O	Yes	P1MAT.7	ADC0.13
				CLU0B.15	CMP0P.9
				CLU1B.13	CMP0N.9
				CLU2A.13	
19	P1.6	Multifunction I/O	Yes	P1MAT.6	ADC0.12
				CLU0A.15	
				CLU1B.12	
				CLU2A.12	
20	P1.5	Multifunction I/O	Yes	P1MAT.5	ADC0.11
				CLU0B.14	
				CLU1A.13	
				CLU2B.13	
				CLU3B.11	
21	P1.4	Multifunction I/O	Yes	P1MAT.4	ADC0.10
				CLU0A.14	
				CLU1A.12	
				CLU2B.12	
				CLU3B.10	
22	P1.3	Multifunction I/O	Yes	P1MAT.3	ADC0.9
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	
23	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	CMP0P.8
				CLU1A.11	CMP0N.8
				CLU2B.10	
				CLU3A.12	
				CLU3B.13	
24	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	CMP0P.7
				CLU1B.10	CMP0N.7
				CLU2A.11	
				CLU3B.12	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
30	P0.3	Multifunction I/O	Yes	P0MAT.3	XTAL2
				EXTCLK	
				INT0.3	
				INT1.3	
				CLU0B.9	
				CLU2B.10	
				CLU3A.9	
31	P0.2	Multifunction I/O	Yes	P0MAT.2	XTAL1
				INT0.2	ADC0.1
				INT1.2	CMP0P.1
				CLU0OUT	CMP0N.1
				CLU0A.9	
				CLU2B.8	
				CLU3A.8	
32	P0.1	Multifunction I/O	Yes	P0MAT.1	ADC0.0
				INT0.1	CMP0P.0
				INT1.1	CMP0N.0
				CLU0B.8	AGND
				CLU2A.9	
				CLU3B.9	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
12	P1.5	Multifunction I/O	Yes	P1MAT.5	ADC0.10
				CLU2OUT	CMP1P.4
				CLU0B.14	CMP1N.4
				CLU1A.13	
				CLU2B.13	
				CLU3B.11	
13	P1.4	Multifunction I/O	Yes	P1MAT.4	ADC0.9
				I2C0_SCL	CMP1P.3
				CLU0A.14	CMP1N.3
				CLU1A.12	
				CLU2B.12	
				CLU3B.10	
14	P1.3	Multifunction I/O	Yes	P1MAT.3	CMP1P.2
				I2C0_SDA	CMP1N.2
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	
15	GND	Ground			
16	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	
				CLU1A.11	
				CLU2B.10	
				CLU3A.12	
				CLU3B.13	
17	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	
				CLU1B.10	
				CLU2A.11	
				CLU3B.12	
18	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU0A.12	
				CLU1A.10	
				CLU2A.10	

6.4 EFM8BB3x-QSOP24 Pin Definitions

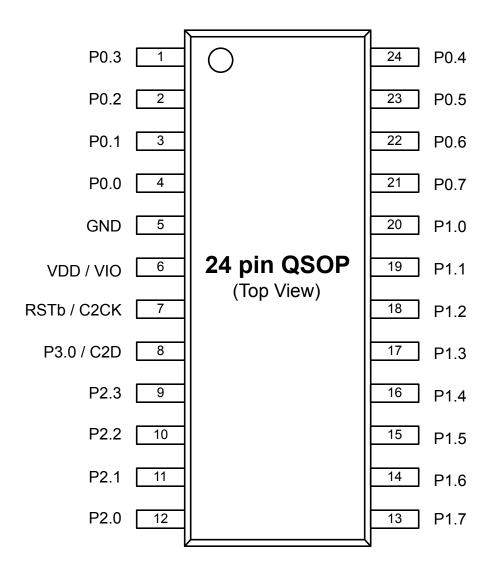


Figure 6.4. EFM8BB3x-QSOP24 Pinout

Table 6.4. Pin Definitions for EFM8BB3x-QSOP24

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
1	P0.3	Multifunction I/O	Yes	P0MAT.3	XTAL2
				EXTCLK	
				INT0.3	
				INT1.3	
				CLU0B.9	
				CLU2B.10	
				CLU3A.9	

Pin	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
Number					
11	P2.1	Multifunction I/O	Yes	P2MAT.1	DAC1
				CLU1B.14	
				CLU2A.15	
				CLU3B.15	
12	P2.0	Multifunction I/O	Yes	P2MAT.0	DAC0
				CLU1A.14	
				CLU2A.14	
				CLU3B.14	
13	P1.7	Multifunction I/O	Yes	P1MAT.7	ADC0.12
				CLU0B.15	CMP1P.6
				CLU1B.13	CMP1N.6
				CLU2A.13	
14	P1.6	Multifunction I/O	Yes	P1MAT.6	ADC0.11
				CLU3OUT	CMP1P.5
				CLU0A.15	CMP1N.5
				CLU1B.12	
				CLU2A.12	
15	P1.5	Multifunction I/O	Yes	P1MAT.5	ADC0.10
				CLU2OUT	CMP1P.4
				CLU0B.14	CMP1N.4
				CLU1A.13	
				CLU2B.13	
				CLU3B.11	
16	P1.4	Multifunction I/O	Yes	P1MAT.4	ADC0.9
				12C0_SCL	CMP1P.3
				CLU0A.14	CMP1N.3
				CLU1A.12	
				CLU2B.12	
				CLU3B.10	
17	P1.3	Multifunction I/O	Yes	P1MAT.3	CMP1P.2
				I2C0_SDA	CMP1N.2
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
18	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	
				CLU1A.11	
				CLU2B.10	
				CLU3A.12	
				CLU3B.13	
19	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	
				CLU1B.10	
				CLU2A.11	
				CLU3B.12	
20	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU0A.12	
				CLU1A.10	
				CLU2A.10	
21	P0.7	Multifunction I/O	Yes	P0MAT.7	ADC0.5
				INT0.7	CMP0P.5
				INT1.7	CMP0N.5
				CLU1OUT	CMP1P.1
				CLU0B.11	CMP1N.1
				CLU1B.9	
				CLU3A.11	
22	P0.6	Multifunction I/O	Yes	P0MAT.6	ADC0.4
				CNVSTR	CMP0P.4
				INT0.6	CMP0N.4
				INT1.6	CMP1P.0
				CLU0A.11	CMP1N.0
				CLU1B.8	
				CLU3A.10	
23	P0.5	Multifunction I/O	Yes	P0MAT.5	ADC0.3
				INT0.5	CMP0P.3
				INT1.5	CMP0N.3
				UART0_RX	
				CLU0B.10	
				CLU1A.9	

9.2 QFN24 PCB Land Pattern

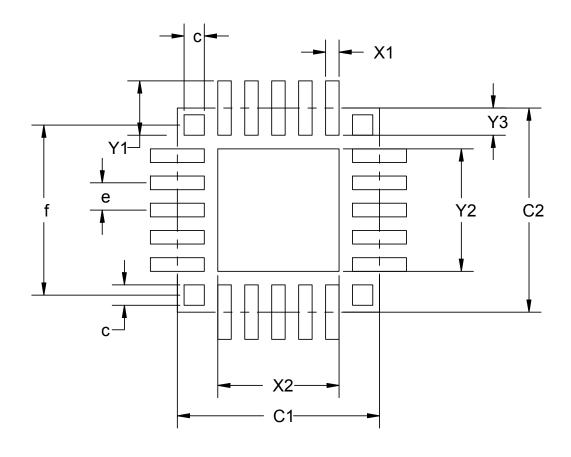


Figure 9.2. QFN24 PCB Land Pattern Drawing

Table 9.2. QFN24 PCB Land Pattern Dimensions

Dimension	Min	Мах		
C1	3.4	00		
C2	3.0	3.00		
е	0.4	REF		
X1	0.:	20		
X2	1.4	80		
Y1	0.	0.80		
Y2	1.80			
Y3	0.4			
f	2.50 REF			
С	0.25	0.35		

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